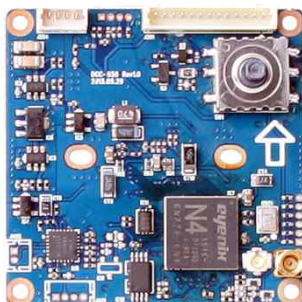
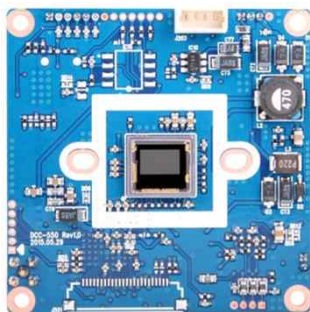


DCC-5560

CMOS VIDEO MODULE

PARANTEK



Main Features

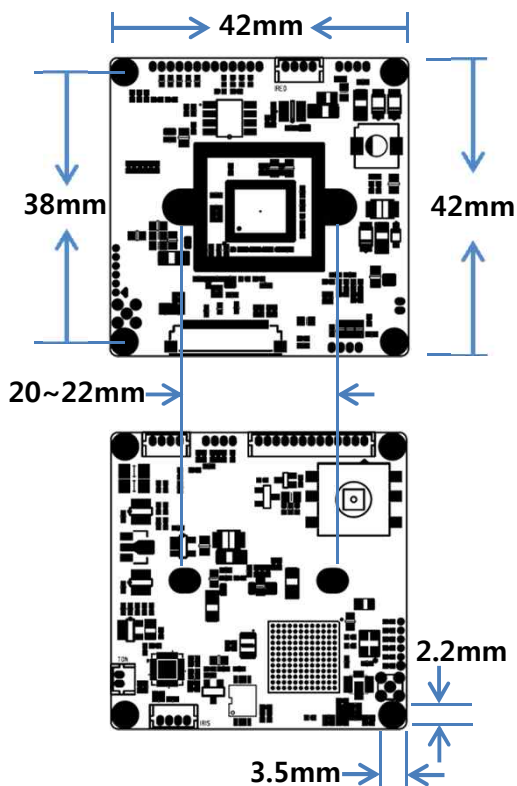
- 1/3" 2.12M(1080P) Panasonic CMOS Image Sensor
- 2Mega Pixels (1080i/P50/60, 1080p25/30, 720P25/30,50/60)
- Mountable Lens: Fixed, Auto VF, Auto ICR VF Lens
- TDN ICR Mechanism Available
- WDR / 3D-NR / DSS(Sens-up) Supported
- OSD Available
- HD-SDI Video Out Supporting standard SMPTE protocol
- EX-SDI Vide Out Supported
- Analog Composite Video Out
- CMOS HD-SDI Video Module (42x42 1-board)



Specifications

Model	DCC-5560
Signal System	HD-SDI (Serial Data Interface) or EX-SDI
Pickup Device	1/3"(D-6mm) 2.12M Panasonic CMOS Sensor
Scanning System	Progressive Scan (16:9)
Sync. System	Internal
Total Pixels	2.22M [2010(H)x1108(V)]
Effective Pixels	2.12M [1944(H)x1092(V)]
Scanning Frequency	30Hz(VD) for NTSC out 25Hz(VD) for PAL out
Min. Illumination	0.06Lux(F2.5 – 30IRE), 0.03Lux(ICR on), 0.002(DSS on)
Mechanical ICR	Available (Option)
H-Resolution	More than 1,000TV Lines(H)
S/N Ratio	More than 50dB (AGC off)
Video Out 1	HD-SDI or EX-SDI: 1080i/p@50/60, 1080p@25/30, 720p@25/30/50/60 From HD-SDI to EX-SDI: Left + Left + Left + Enter From EX-SDI to HD-SDI: Right + Right + Right + Enter
Video Out 2	Composite Video 1V p.p (NTSC/PAL - 75Ω)
Lens	DC Auto & Fixed Iris Lens
Lens (Mount)	Board (M12) and VF (Ø14) – Lens Holder
OSD	Option: Built-in OSD Switch or OSD Board
Camera Title	Off, On(Max. 10 Characters)
Language	English, Chinese(Simplified), Chinese(Traditional), Japanese, Korean
Exposure	DC, Manual
White Balance	AWB, ATW, Push Lock, Manual
BLC	Off, HLC, BLC, WDR * WDR is not operated when manual shutter mode or CVBS output mode is selected.
Day & Night Mode	AUTO, COLOR, B/W, EXT
Gain Control	AGC (0~20)
Electronic Shutter	1/25(30)~1/30,000sec
Noise Reduction	3DNR (Off, Low, Middle, High)
DSS(Sens-up)	X32
Mirror	Off, On(Mirror, Flip)
Other Features	Motion Detection (4 Zones), Privacy Mask (16 Zones), Flickerless, Lens Shading, Gamma, D-zoom, Defog etc.
Power Source	DC12V
Power Consumption	Less than 2.4 Watts (200mA)
Operating Temp.	-10℃ ~ 55℃ (Humidity :0%RH ~ 90%RH)
Size (mm)	42(W) x 42(D) – 1 board
Weight	10 g (Including OLPF)

Dimension



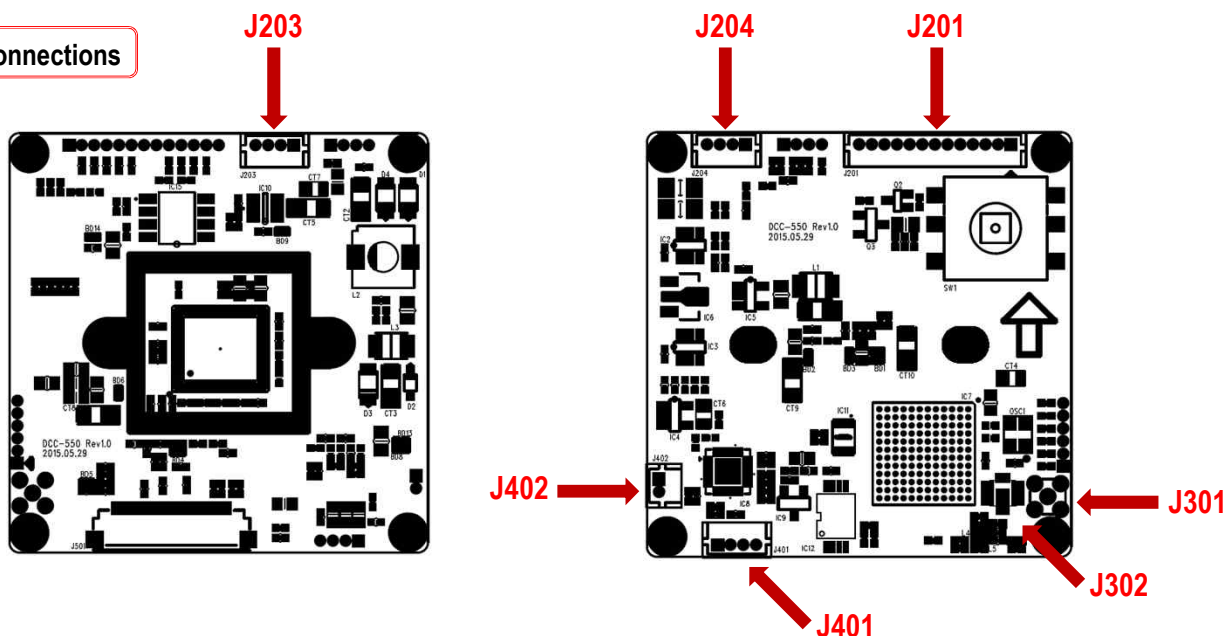
Option

- Mechanical TDN ICR
- Lens

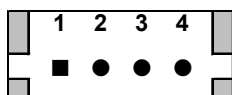
DCC-5560

CMOS VIDEO MODULE

Pin Connections



J401 – DC IRIS



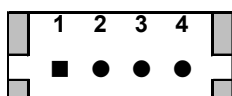
No.	Pin Item	No.	Pin Item
1	DMP+	3	DRV+
2	DMP-	4	GND

Wafer DIP type: **1.25mm pitch – 4 pin**

Manufacturer: **Molex**

MFG Part Number: **53047-0410**

J203 – IR LED Board



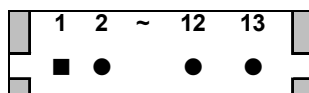
No.	Pin Item	No.	Pin Item
1	DC12V	3	EXT_DN (CDS)
2	GND	4	D&N OUT

Wafer DIP type: **1.25mm pitch – 4 pin**

Manufacturer: **Molex**

MFG Part Number: **53047-0410**

J201 – RS485 / OSD etc.



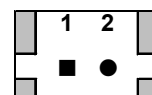
No.	Pin Item	No.	Pin Item
1	GND	8	EXT DO (B/W: High 3.3V)
2	KEY_DOWN	9	RS485 TTL 3.3V TXD
3	KEY_UP	10	RS485 TTL 3.3V RXD
4	KEY_SET	11	RS485 EN
5	KEY_RIGHT	12	RS485 REG
6	KEY_LEFT	13	DC 3.3V
7	EXT DI (B/W: Low 0V)		

Wafer DIP type: **1.25mm pitch – 13 pin**

Manufacturer: **Yeonho**

MFG Part Number: **12512WS-13B**

J402 – TDN ICR



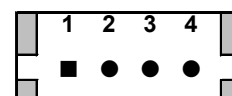
No.	Pin Item	No.	Pin Item
1	ICR (+)	2	ICR (-)

Wafer DIP type: **1.25mm pitch – 2 pin**

Manufacturer: **Yeonho**

MFG Part Number: **12512WS-02B**

J204 – Power & CVBS



No.	Pin Item	No.	Pin Item
1	CVBS	3	DC12V
2	GND	4	GND

Wafer DIP type: **1.25mm pitch – 3/4 pin**

Manufacturer: **Yeonho / Molex**

MFG Part Number: **12512WS-03B / 53047-0410**

J301 – HD-SDI Out - MMCX

J302 – HD-SDI Out - MHF